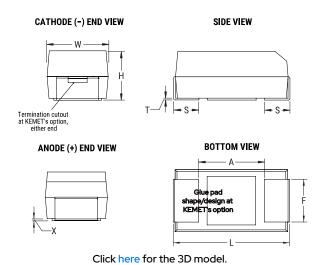


## T591V157M006ATE025

T591, Tantalum, Polymer Tantalum, 150 uF, 20%, 6.3 VDC, SMD, Polymer, Molded, Low ESR, 25 mOhms, 7343, 2 mm, 1.3 mm



General Information		
Series	T591	
Dielectric	Polymer Tantalum	
Style	SMD Chip	
Description	SMD, Polymer, Molded, Low ESR	
Features	Automotive	
RoHS	Yes	
Termination	Tin	
Qualifications	AEC-Q200 (Limited 500 Hrs 85C/85% RH/Ur)	
AEC-Q200	Subject to PPAP/PSW and change control	
Typical Component Weight	274.3 mg	
Shelf Life	52 Weeks	
MSL	3	

150 uF

7.3mm +/-0.3mm
4.3mm +/-0.3mm
1.9mm +/-0.1mm
0.13mm REF
1.3mm +/-0.3mm
2.4mm +/-0.1mm
3.8mm MIN
0.05mm REF

W	4.3mm +/-0.3mm	Tolerance	20%
Н	1.9mm +/-0.1mm	Voltage DC	6.3 VDC (105C), 4.22 VDC
Т	0.13mm REF		(125C)
S	1.3mm +/-0.3mm	Temperature Range	-55/+125°C
	,	Rated Temperature	105°C
F	2.4mm +/-0.1mm	Humidity	85C, 85% RH, load, 500 H
Α	3.8mm MIN	•	
X 0.05mm REF	0.05mm REF	Dissipation Factor	10% 120Hz 25C
^	0.03mmnLi	Failure Rate	N/A
Packaging Specifications		ESR	25 mOhms (100kHz 25C)
Packaging	T&R, 178mm	Ripple Current	4000 mA (rms, 100kHz 45 2800 mA (rms, 105C), 100

Н	1.9mm +/-0.1mm	Voltage DC	6.3 VDC (105C), 4.22 VDC (125C)
Т	0.13mm REF	Temperature Range	-55/+125°C
S 1.3mm +/-0.3mm	1.3mm +/-0.3mm	Rated Temperature	105°C
F	2.4mm +/-0.1mm	Humidity	85C, 85% RH, load, 500 Hours
A	3.8mm MIN	Dissipation Factor	10% 120Hz 25C
X	0.05mm REF	Failure Rate	N/A
Packaging Specifications		ESR	25 mOhms (100kHz 25C)
Packaging	T&R, 178mm	Ripple Current	4000 mA (rms, 100kHz 45C), 2800 mA (rms, 105C), 1000 mA (rms, 125C)
Packaging Quantity	1000		
		Leakage Current	94.5 uA (5min 25°C)

**Specifications** 

Capacitance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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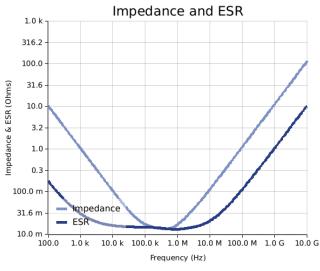


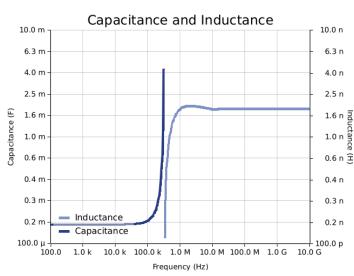


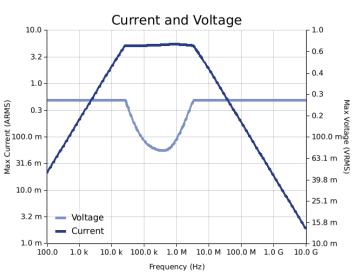
T591, Tantalum, Polymer Tantalum, 150 uF, 20%, 6.3 VDC, SMD, Polymer, Molded, Low ESR, 25 mOhms, 7343, 2 mm, 1.3 mm

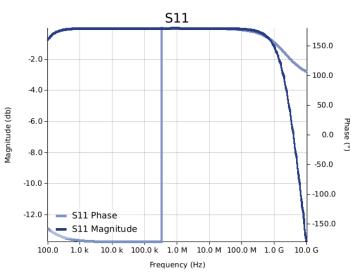
## **Simulations**

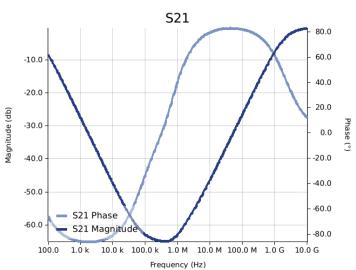
For the complete simulation environment please visit K-SIM.











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## T591V157M006ATE025

T591, Tantalum, Polymer Tantalum, 150 uF, 20%, 6.3 VDC, SMD, Polymer, Molded, Low ESR, 25 mOhms, 7343, 2 mm, 1.3 mm

## These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for ripple Ripple Currenty votage vs. rrequency plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
  The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
  The effects shown herein are based on measured data from a multiple part sample of the parts in question.
  Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
  The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

   Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

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